

ABSTRACT OF THE DISCLOSURE

An assembly substrate on which a plurality of semiconductor chips each having a terminal receiving a burn-in test waveform are arranged is detachably attached to a burn-in test adapter. The burn-in
5 test adapter has a wiring arranged in such a manner that, when the assembly substrate is attached to the burn-in test adapter, the wiring makes an electrical contact with the terminal of each of the semiconductor chips on the assembly substrate. Moreover, the burn-in
10 test adapter has a burn-in test terminal that is electrically connected to the wiring and that receives the burn-in test waveform.